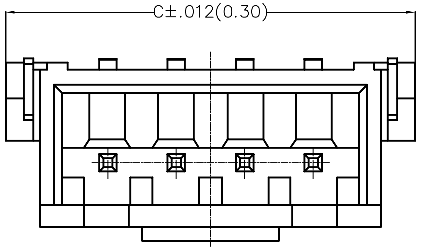
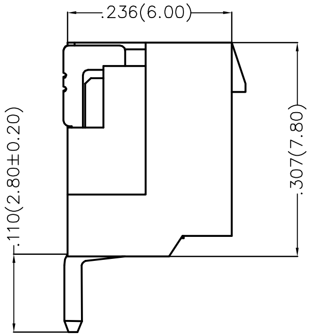
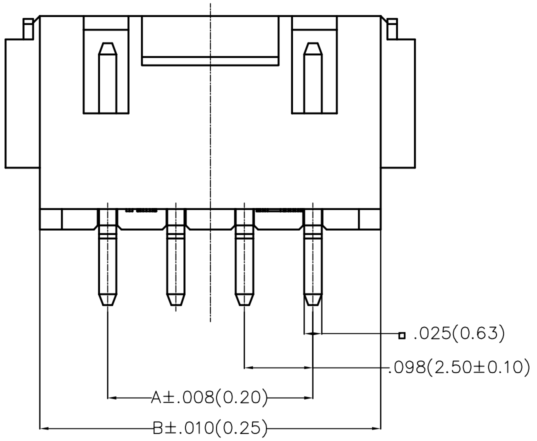
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	⚠	Correct the Color-Resin	01/APR/26	MATT	LEO

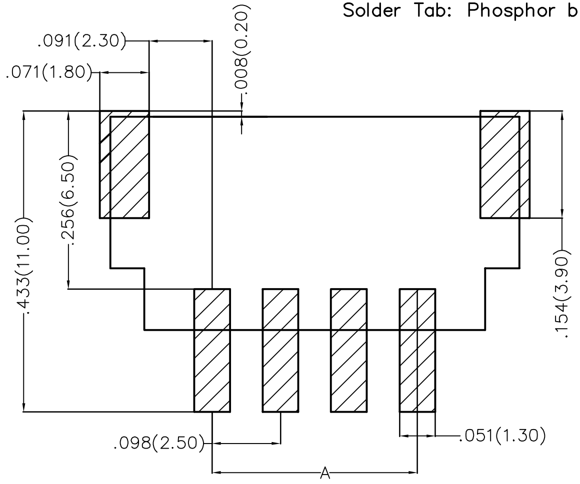
Electrical
- Current Rating: 3A AC(rms)/DC
- Voltage Rating: 250V AC(rms)/DC
- Contact Resistance: 20 mΩ Max
- Insulation Resistance: 1000 MΩ MIN
- Withstanding Voltage: 1000V AC r.m.s
- Temperature Range—Operating: −25°C～+85°C

Material and Plating
- Housing: PA9T UL 94V−0
- Contact Pin: Brass
- Plating: Tin Plated
- Solder Tab: Phosphor bronze









Recommended P.C.Board Layout

Ordering Information

FWF	250	30	—	S	XX	B	2	5	W5	M
1	2	3		4	5	6	7	8	9	10

No.	Item	Option
1	Category	FWF—Wafer
2	Series Number	250—Pitch2.50mm
3	Distinction No.	30
4	Row Option	S—Single Row
5	Circuits	XX
6	Entry Angle	B—90° Angle
7	Plating	2—Tin Plated
8	Material—Resin	5—PA9T
9	Color—Resin	W5—Natural ⚠
10	Packaging	M—Reel

THIRD ANGLE PROJECTION

DESIGN UNITS
Metric

SCALE 5:1
SIZE A4

GENERAL TOLERANCES (UNLESS SPECIFIED)

X. ±0.30	X.° ±5°
X.X ±0.20	X.X° ±2°
X.XX ±0.15	X.XX° ±1°
X.XXX ±0.10	X.XXX° ±0.5°

APPROVE BY	FRANK	DATE 06/JUN/17
CHECKED BY	CHERRY	DATE 06/JUN/17
DRAWN BY	LXF	DATE 06/JUN/17

PART NO. FWF25030-SXXB25W5M
ITEM NO. FWF25030

TITLE
Wire to Board (Wafer)
Pitch 2.5mm 90° Anglel (SMT)

TXGA
Building Technology Cornerstone

REV 1
SHEET NO. 1/2

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part NO.	Dimension(in/mm)		
		A	B	C
2	FWF25030-S02B25W5M	.098(2.50)	.295(7.50)	.394(10.00)
3	FWF25030-S03B25W5M	.197(5.00)	.394(10.00)	.492(12.50)
4	FWF25030-S04B25W5M	.295(7.50)	.492(12.50)	.591(15.00)
5	FWF25030-S05B25W5M	.394(10.00)	.591(15.00)	.689(17.50)
6	FWF25030-S06B25W5M	.492(12.50)	.689(17.50)	.787(20.00)
8	FWF25030-S08B25W5M	.689(17.50)	.886(22.50)	.984(25.00)

THIRD ANGLE PROJECTION

DESIGN UNITS
Metric

SCALE 5:1
SIZE A4

GENERAL TOLERANCES
(UNLESS SPECIFIED)

X. ±0.30	X.° ±5°
X.X ±0.20	X.X° ±2°
X.XX ±0.15	X.XX° ±1°
X.XXX ±0.10	X.XXX° ±0.5°

APPROVE BY FRANK	DATE 06/JUN/17
CHECKED BY CHERRY	DATE 06/JUN/17
DRAWN BY LXF	DATE 06/JUN/17

PART NO.
FWF25030-SXXB25W5M

ITEM NO.
FWF25030

TXGA
Building Technology Cornerstone

TITLE
Wire to Board (Wafer)
Pitch 2.5mm 90° Anglel (SMT)

REV 1
SHEET NO. 2/2